



#### **FEATURES**

- Member of the Texas Instruments Widebus+™
  Family
- Operates From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t<sub>pd</sub> of 4 ns at 3.3 V
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot) > 2 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V<sub>CC</sub>)

## **DESCRIPTION/ORDERING INFORMATION**

This 32-bit noninverting bus transceiver is designed for 1.65-V to 3.6-V V<sub>CC</sub> operation.

The SN74LVC32245 is designed for asynchronous communication between data buses. The control-function implementation minimizes external timing requirements.

This device can be used as four 8-bit transceivers, two 16-bit transceivers, or one 32-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable  $(\overline{OE})$  input can be used to disable the device so that the buses are effectively isolated.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

#### **ORDERING INFORMATION**

T <sub>A</sub>	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
40°C to 95°C	LFBGA – GKE	Tape and reel	SN74LVC32245GKER	NC24E	
-40°C 10 85°C	C to 85°C LFBGA – ZKE (Pb-free)		SN74LVC32245ZKER	NC245	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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Widebus+ is a trademark of Texas Instruments.



# GKE OR ZKE PACKAGE (TOP VIEW)

1 2 3 4 5 6 000000 Α 000000 В 000000 С 000000 D 000000 Ε F 000000 000000 G 000000 Н 000000 J 000000 Κ L 000000 000000 M 000000 Ν 000000 Ρ 000000 R Т 000000

#### **TERMINAL ASSIGNMENTS**

	1	2	3	4	5	6
Α	1B2	1B1	1DIR	1 <del>OE</del>	1A1	1A2
В	1B4	1B3	GND	GND	1A3	1A4
С	1B6	1B5	$V_{CC}$	V <sub>CC</sub>	1A5	1A6
D	1B8	1B7	GND	GND	1A7	1A8
E	2B2	2B1	GND	GND	2A1	2A2
F	2B4	2B3	$V_{CC}$	V <sub>CC</sub>	2A3	2A4
G	2B6	2B5	GND	GND	2A5	2A6
Н	2B7	2B8	2DIR	2 <del>OE</del>	2A8	2A7
J	3B2	3B1	3DIR	3 <del>OE</del>	3A1	3A2
K	3B4	3B3	GND	GND	3A3	3A4
L	3B6	3B5	$V_{CC}$	V <sub>CC</sub>	3A5	3A6
M	3B8	3B7	GND	GND	3A7	3A8
N	4B2	4B1	GND	GND	4A1	4A2
Р	4B4	4B3	V <sub>CC</sub>	V <sub>CC</sub>	4A3	4A4
R	4B6	4B5	GND	GND	4A5	4A6
Т	4B7	4B8	4DIR	4 <del>0E</del>	4A8	4A7

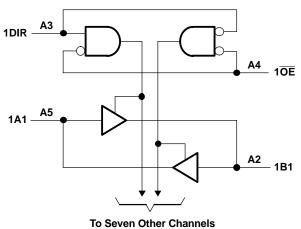


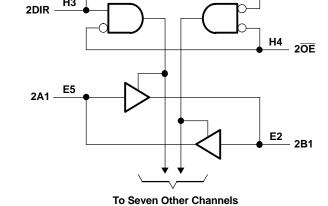
### **FUNCTION TABLE** (EACH 8-BIT SECTION)

INP	UTS	OPERATION
ŌĒ	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	X	Isolation

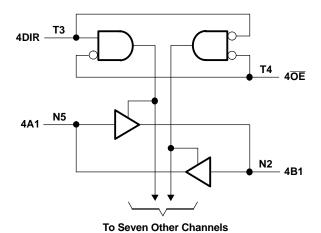
### **LOGIC DIAGRAM (POSITIVE LOGIC)**

Н3





J3 3DIR -J4 3A1 -J2 3B1 To Seven Other Channels



## SN74LVC32245 32-BIT BUS TRANSCEIVER WITH 3-STATE OUTPUTS

SCES343D-OCTOBER 2000-REVISED APRIL 2005



## **Absolute Maximum Ratings**(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage range		-0.5	6.5	٧
VI	Input voltage range <sup>(2)</sup>		-0.5	6.5	V
Vo	Voltage range applied to any output in the h	igh-impedance or power-off state (2)	-0.5	6.5	V
Vo	Voltage range applied to any output in the h	-0.5	V <sub>CC</sub> + 0.5	V	
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through each V <sub>CC</sub> or GN	ID		±100	mA
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>	GKE/ZKE package		40	°C/W
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## Recommended Operating Conditions<sup>(1)</sup>

			MIN	MAX	UNIT	
.,	Complexed to an	Operating	1.65	3.6	V	
V <sub>CC</sub>	Supply voltage	Data retention only	1.5		V	
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>			
$V_{IH}$	High-level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		V	
		V <sub>CC</sub> = 2.7 V to 3.6 V	2			
		V <sub>CC</sub> = 1.65 V to 1.95 V		$0.35 \times V_{CC}$		
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V		0.7	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		
VI	Input voltage		0	5.5	V	
.,	O Output voltage	High or low state	0	V <sub>CC</sub>	V	
Vo		3-state	0	5.5	V	
		V <sub>CC</sub> = 1.65 V		-4		
	Lligh lovel output ourrent	V <sub>CC</sub> = 2.3 V		-8	mA	
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2.7 V		-12	ША	
		V <sub>CC</sub> = 3 V		-24		
		V <sub>CC</sub> = 1.65 V		4		
	Low level output ourrent	V <sub>CC</sub> = 2.3 V		8	mA	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2.7 V		12	MA	
		V <sub>CC</sub> = 3 V		24		
Δt/Δν	Input transition rise or fall rate			5	ns/V	
T <sub>A</sub>	Operating free-air temperature		-40	85	°C	

<sup>(1)</sup> All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

<sup>(2)</sup> The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>(3)</sup> The value of V<sub>CC</sub> is provided in the recommended operating conditions table.

<sup>(4)</sup> The package thermal impedance is calculated in accordance with JESD 51-7.



## SN74LVC32245 **32-BIT BUS TRANSCEIVER** WITH 3-STATE OUTPUTS

#### **Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

P/	RAMETER	TEST CO	ONDITIONS	V <sub>cc</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT		
		$I_{OH} = -100 \mu A$		1.65 V to 3.6 V	$V_{CC} - 0.2$					
		$I_{OH} = -4 \text{ mA}$		1.65 V	1.2					
\/		$I_{OH} = -8 \text{ mA}$		2.3 V	1.7			V		
V <sub>OH</sub>		I <sub>OH</sub> = −12 mA		2.7 V	2.2			V		
		10H = -12 IIIA		3 V	2.4					
		$I_{OH} = -24 \text{ mA}$		3 V	2.2					
		$I_{OL} = 100  \mu A$		1.65 V to 3.6 V			0.2			
		I <sub>OL</sub> = 4 mA		1.65 V	0.45					
V <sub>OL</sub>		$I_{OL} = 8 \text{ mA}$		2.3 V			0.7	V		
		I <sub>OL</sub> = 12 mA		2.7 V			0.4			
		I <sub>OL</sub> = 24 mA		3 V			0.55			
$I_{\parallel}$	Control inputs	V <sub>I</sub> = 0 to 5.5 V		3.6 V			±5	μΑ		
$I_{\rm off}$		$V_I$ or $V_O = 5.5 \text{ V}$		0			±10	μΑ		
$I_{OZ}^{(2)}$		$V_0 = 0 \text{ to } 5.5 \text{ V}$		2.3 V to 3.6 V			±5	μΑ		
		$V_I = V_{CC}$ or GND	1 -0	3.6 V	2		20	^		
I <sub>CC</sub>		$3.6 \text{ V} \le V_1 \le 5.5 \text{ V}^{(3)}$	$I_{O} = 0$	3.0 V			20	μΑ		
$\Delta I_{CC}$		One input at V <sub>CC</sub> – 0.6 V,	Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V			500	μΑ		
$C_{i}$	Control inputs	$V_I = V_{CC}$ or GND		3.3 V		5		pF		
$C_{io}$	A or B ports	$V_O = V_{CC}$ or GND		3.3 V		7.5		pF		

### **Switching Characteristics**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = ± 0.1		V <sub>CC</sub> = : ± 0.2		V <sub>CC</sub> =	2.7 V	V <sub>CC</sub> = 3 ± 0.3	3.3 V 3 V	UNIT
	(INFOT)	(001F01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A or B	B or A	1.5	7.1	1	4.5	1	4.7	1	4	ns
t <sub>en</sub>	ŌĒ	A or B	1.5	8.9	1	5.6	1.5	6.7	1.5	5.5	ns
t <sub>dis</sub>	ŌĒ	A or B	1.5	11.9	1	6.8	1.5	7.1	1.5	6.6	ns
t <sub>sk(o)</sub>										1	ns

## **Operating Characteristics**

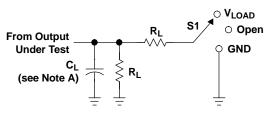
 $T_A = 25^{\circ}C$ 

	PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V TYP	V <sub>CC</sub> = 2.5 V TYP	V <sub>CC</sub> = 3.3 V TYP	UNIT	
_	Power dissipation capacitance	Outputs enabled	f = 10 MHz	34	37	38	~F	
C <sub>pd</sub>	per transceiver	Outputs disabled	I = IU IVIMZ	3	3	4	pF	

<sup>(1)</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ . (2) For I/O ports, the parameter  $I_{OZ}$  includes the input leakage current. (3) This applies in the disabled state only.



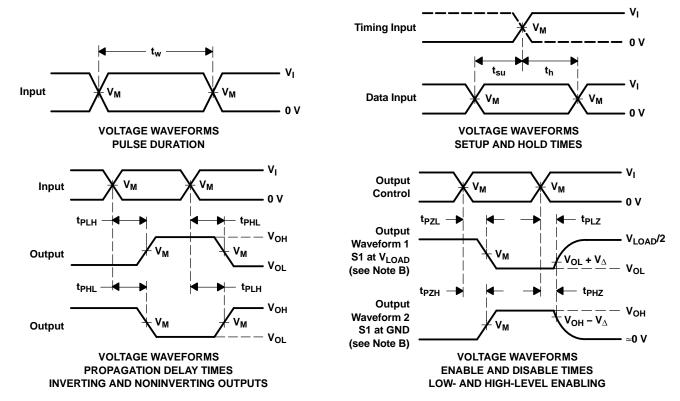
#### PARAMETER MEASUREMENT INFORMATION



TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>LOAD</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

**LOAD CIRCUIT** 

	INF	PUTS	.,	.,		_	.,
V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	R <sub>L</sub>	$oldsymbol{V}_{\Delta}$
1.8 V ± 0.15 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	<b>1 k</b> Ω	0.15 V
2.5 V $\pm$ 0.2 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V $\pm$ 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω.
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



## PACKAGE OPTION ADDENDUM

27-Dec-2019

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74LVC32245GKER	NRND	LFBGA	GKE	96	1000	TBD	SNPB	Level-2-235C-1 YEAR	-40 to 85	NC245	
SN74LVC32245ZKER	NRND	LFBGA	ZKE	96	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR	-40 to 85	NC245	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

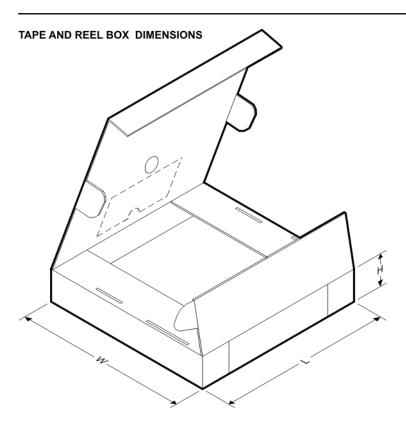
### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC32245GKER	LFBGA	GKE	96	1000	330.0	24.4	5.7	13.7	2.0	8.0	24.0	Q1
SN74LVC32245ZKER	LFBGA	ZKE	96	1000	330.0	24.4	5.7	13.7	2.0	8.0	24.0	Q1

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC32245GKER	LFBGA	GKE	96	1000	336.6	336.6	41.3
SN74LVC32245ZKER	LFBGA	ZKE	96	1000	336.6	336.6	41.3

# GKE (R-PBGA-N96)

## PLASTIC BALL GRID ARRAY



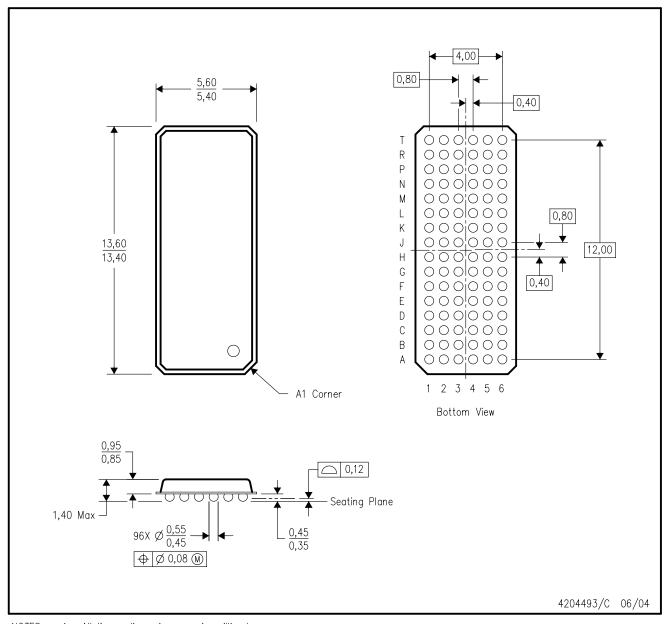
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-205 variation CC.
- D. This package is tin-lead (SnPb). Refer to the 96 ZKE package (drawing 4204493) for lead-free.



# ZKE (R-PBGA-N96)

## PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-205 variation CC.
- D. This package is lead-free. Refer to the 96 GKE package (drawing 4188953) for tin-lead (SnPb).



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